

Title (en)

Ultrathin copper foil with carrier and printed circuit board using same

Title (de)

Ultradünne Kupferfolie mit Träger und Leiterplatte und dessen Verwendung

Title (fr)

Feuille de cuivre ultra-mince avec support et circuit imprimé l'utilisant

Publication

EP 1802183 B1 20091104 (EN)

Application

EP 06025857 A 20061213

Priority

- JP 2005361311 A 20051215
- JP 2006303303 A 20061108

Abstract (en)

[origin: EP1802183A2] An ultrathin copper foil with a carrier not causing blistering at a release layer interface, having a low carrier peeling force, friendly to the environment, and enabling easy peeling of a carrier foil and an ultrathin copper foil even under a high temperature environment and a printed circuit board enabling a stable production quality of a base of a printed circuit board for fine pattern applications using the ultrathin copper foil with the carrier, that is, a ultrathin copper foil with a carrier comprising a carrier foil, a diffusion prevention layer, a release layer, and an ultrathin copper foil, wherein the release layer is formed by a metal A for retaining a release property and a metal B for facilitating plating of the ultrathin copper foil, a content a of the metal A and a content b of the metal B forming the release layer satisfying an equation: and a printed circuit board prepared by using such a ultrathin copper foil with a carrier.

IPC 8 full level

H05K 3/02 (2006.01)

CPC (source: EP KR US)

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Cited by

CN103974549A; EP4132237A3; CN105074058A; CN103392028A; TWI513388B; WO2016107649A1

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